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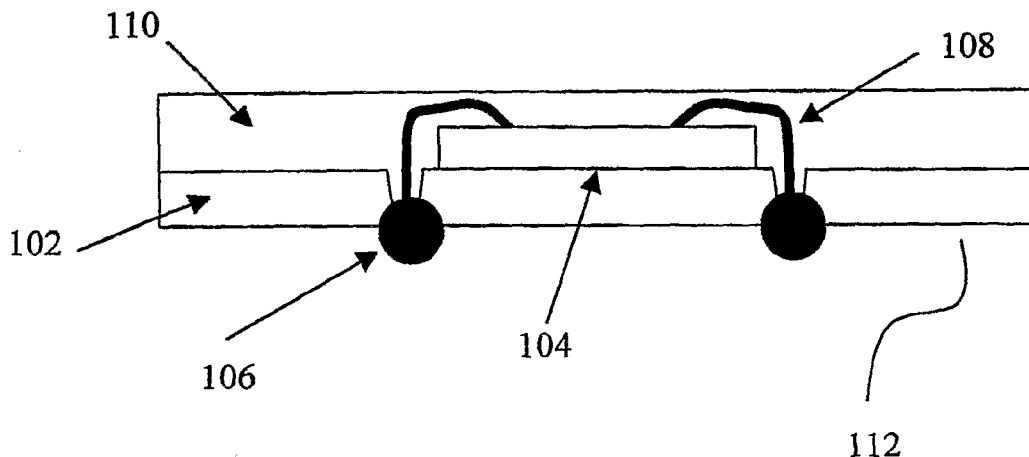
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(54) Title: INTEGRATED BALL AND VIA PACKAGE AND FORMATION PROCESS



(57) Abstract: A method of processing a semiconductor device is provided. The method includes providing a semiconductor device supported by a carrier structure. The carrier structure defines a plurality of vias from a first surface of the carrier structure adjacent the semiconductor device to a second surface of the carrier structure. The method also includes extending a conductor through one of the vias such that a first end of the conductor at least partially extends below the second surface. The method also includes electrically coupling another portion of the conductor to a portion of the semiconductor device.

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